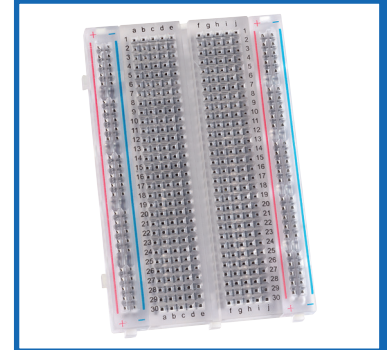# R-TECH

Solderless Transparent Breadboard – 400 Points

DESCRIPTION

This 400-point transparent solderless breadboard allows components to be easily connected & disconnected.

DISTINCTIVE FEATURES

- Solderless concept allows reuse of components
- Two 30 x 5 strips with two 25 x 2 power rails
- Total of 400 tie points
- Components are retained by spring contacts
- Sockets are on a 2.54mm matrix
- Contact positions defined on an alphanumeric grid
- ABS Polymer board on an adhesive foam base
- Wire sizes 0.288 to 0.841mm (29 to 20 AWG)
- Dimensions: 83.5 x 54.5 x 8.5mm
- Boards can be slotted together for larger circuits

APPLICATIONS

Ideal for use for prototyping, circuit design, electronic projects. The transparent design makes it especially useful in training and education. Matrix layout enables DIL components to be utilised.

400 Points

Solderless

Transparent

Power Rails

2.54mm Matrix

R-TECH

GENERAL SPECIFICATION

Series	Solderless Breadboard
Type	Transparent square hole style
Number of tie points	400
Wire size	0.288 to 0.841mm (29 to 20 AWG)

ELECTRICAL SPECIFICATION

Voltage rating	300V
Current rating	3 to 5A

MATERIALS

Material	ABS Polymer
Colour	Transparent
Contact material	Nickel plated phosphor bronze

ENVIRONMENTAL/OPERATING SPECIFICATION

Heat distortion temperature (POM)	150°C
Heat distortion temperature (ABS)	84°C
Contact Life	50,000 insertions

TERMINALS

Contacts	Double-leaf spring contacts

Units	mm - unless stated otherwise
Dimensions	83.5 x 54.5 x 8.5mm
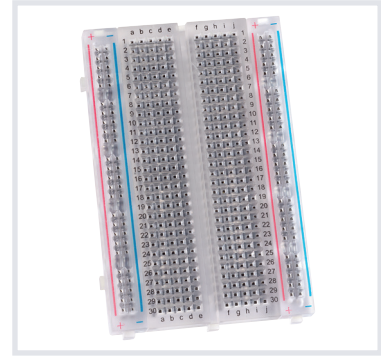
PART NUMBER TABLE

Part Number	EAN	UNSPSC	Country of Origin
34-1320	5053556002566	32101510	China

R-TECH
Tried & trusted technology